

IN THE CLAIMS:

- 1 1. A method of packaging a semiconductor, comprising:
2 applying a semiconductor epoxy to a semiconductor;
3 dispensing a substrate epoxy onto a packaging substrate; and
4 engaging said substrate epoxy with said semiconductor epoxy.
- 1 2. The method of claim 1 wherein said applying includes applying a relatively
2 thick layer of semiconductor epoxy to said semiconductor.
- 1 3. The method of claim 2 wherein said applying includes applying approximately
2 5 mils or more of semiconductor epoxy to said semiconductor.
- 1 4. The method of claim 1 wherein said applying includes applying said
2 semiconductor epoxy to said semiconductor by spinning.
- 1 5. The method of claim 1 wherein said applying includes curing said
2 semiconductor epoxy.
- 1 6. The method of claim 1 wherein said dispensing includes dispensing a relatively
2 thin layer of substrate epoxy onto said packaging substrate.
- 1 7. The method of claim 6 wherein said dispensing includes dispensing
2 approximately 2 mils or less of substrate epoxy onto said packaging substrate.
- 1 8. The method of claim 1 wherein said dispensing includes machine dispensing
2 said substrate epoxy onto a lead frame.
- 1 9. The method of claim 1 wherein said dispensing results in a substrate epoxy
2 layer and said applying results in a semiconductor epoxy layer that is approximately
3 2.5 times or more thicker than said substrate epoxy layer.

1 10. The method of claim 1 further comprising wire bonding said semiconductor to
2 said packaging substrate.

1 11. The method of claim 10 further comprising enclosing said packaging substrate
2 and said semiconductor in a housing.

1 12. A semiconductor package, comprising:
2 a relatively thin substrate epoxy attached to a packaging substrate;
3 a relatively thick semiconductor epoxy attached to a semiconductor, wherein
4 said relatively thin substrate epoxy and said relatively thick semiconductor epoxy are
5 attached to one another forming a stack including said packaging substrate, said
6 relatively thin substrate epoxy, said relatively thick semiconductor epoxy, and said
7 semiconductor; and
8 a housing enclosing said stack.

1 13. The semiconductor package of claim 12 wherein said relatively thick
2 semiconductor epoxy is approximately 2.5 times or more as thick as said relatively
3 thin substrate epoxy.

1 14. The semiconductor package of claim 12 wherein said relatively thick
2 semiconductor epoxy is approximately 5 mils or more.

1 15. The semiconductor package of claim 12 wherein said relatively thin substrate
2 epoxy is approximately 2 mils or less.

1 16. The semiconductor package of claim 12 wherein said packaging substrate is a
2 lead frame.